



Material Content Data Sheet



Sales Product Name		BTS134D		Issued		25. January 2018		
MA#		MA000950996						
Package		PG-TO252-3-11		Weight*		371.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.370	0.91	0.91	9078	9078
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		580	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	copper	7440-50-8	215.017	57.91	57.99	579254	580008
wire	non noble metal	aluminium	7429-90-5	1.075	0.29	0.29	2896	2896
encapsulation	organic material	carbon black	1333-86-4	1.254	0.34		3378	
	plastics	epoxy resin	-	21.946	5.91		59123	
	inorganic material	silicondioxide	60676-86-0	102.206	27.53	33.78	275342	337843
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10076	10076
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246
solder	noble metal	silver	7440-22-4	0.075	0.02		203	
	non noble metal	tin	7440-31-5	0.060	0.02		162	
	non noble metal	lead	7439-92-1	2.879	0.78	0.82	7756	8121
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51664	51732
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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